



<b>Title of Change:</b>	Update Notice of FPCN20937X - Reliability Data update of NTMFS4C05NT1G.
<b>Proposed first ship date:</b>	17 December 2015
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <MohdHezri.AbuBakar@onsemi.com>
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <Michael.Mooney@onsemi.com>
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Don.Knudsen@onsemi.com>
<b>Type of notification:</b>	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
<b>Change category:</b>	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____

<b>Change Sub-Category(s):</b>		<input type="checkbox"/> Datasheet/Product Doc change
<input checked="" type="checkbox"/> Manufacturing Site Change/Addition	<input type="checkbox"/> Material Change	<input type="checkbox"/> Shipping/Packaging/Marking
<input type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Product specific change	<input type="checkbox"/> Other: _____

<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) :	<input checked="" type="checkbox"/> External Foundry/Subcon site(s) Aizu Fujitsu Semiconductor Manufacturing, Japan
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**Description and Purpose:**  
 This Update Notification is issued to customers to provide updated Reliability data of HTRB and HTGB at 1008 hrs from the qualification vehicle of NTMFS4C05NT1G.

FPCN20937X was issued to customers on the qualification of the additional wafer fabrication capacity of 30V Trench (T6) MOSFET technology in Aizu Fujitsu Semiconductor Manufacturing (AFSM) located in Aizu, Japan. At the expiration of the notification, all products listed here will be dual sourced from its current ON Semiconductor wafer fab in Gresham and AFSM.

**Reliability Data Summary:**

**QV Name: NTMFS4C05NT1G**  
**Package: SO8FL**

Test	Specification	Condition	Interval	Sample Size	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated Vdss	1008 hrs	80 pcs/3 lots	0/240
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	80 pcs/3 lots	0/240
HTSL	JESD22-A103	Ta=150°C	2016 hrs	80 pcs/3 lots	0/240
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	80 pcs/3 lots	0/240
TC	JESD22-A104	Ta=-55°C to +150°C	2000 cyc	80 pcs/3 lots	0/240
HAST	JESD22-A110	131°C, 85% RH, 18.8psig, bias	96 hrs	80 pcs/3 lots	0/240
uHAST	JESD22-A118	131°C, 85% RH, 18.8psig, unbiased	96 hrs	80 pcs/3 lots	0/240

**Electrical Characteristic Summary:**  
 There is no change in electrical parametric performance. Characterization data is available upon request.

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
NTMFS4C05NT1G	NTMFS4C05NT1G
NTMFS4C05NT3G	NTMFS4C05NT1G
NTMFS4C06NT1G	NTMFS4C05NT1G
NTMFS4C08NT1G	NTMFS4C05NT1G
NTMFS4C08NT3G	NTMFS4C05NT1G
NTMFS4C09NT1G	NTMFS4C05NT1G
NTMFS4C09NT3G	NTMFS4C05NT1G
NTMFS4C10NT1G	NTMFS4C05NT1G
NTMFS4C13NT1G	NTMFS4C05NT1G
NTMFS4C13NT3G	NTMFS4C05NT1G
NTMFS4C35NT1G	NTMFS4C05NT1G
NTMFS4C35NT3G	NTMFS4C05NT1G